

AMENDMENTS TO THE CLAIMS:

Please cancel Claims 5-7 and 27-29, and add Claims 41-46 as follows:

1. (original) A method of fabricating a micromechanical device, the method comprising:
 - forming at least two micromechanical devices on a common substrate;
 - overcoating said micromechanical devices using vapor deposition;
 - separating said common substrate to separate said devices; and
 - removing said overcoat from said micromechanical devices.
2. (original) The method of Claim 1, said vapor deposition comprising:
 - providing a plasma of an organic gas;
 - generating reactive intermediaries of said plasma; and
 - depositing said reactive intermediaries on said micromechanical devices.
3. (original) The method of Claim 2, said organic gas comprising vinylic hydrocarbons.
4. (original) The method of Claim 2, said organic gas comprising fluorocarbons.
5. (canceled)
6. (canceled)
7. (canceled)
8. (original) The method of Claim 1, said vapor deposition comprising:
 - providing an organic gas;
 - exposing said organic gas to at least one electrical conductor held at a high voltage potential to generate reactive intermediaries of said organic gas; and
 - depositing said reactive intermediaries on said micromechanical devices.
9. (original) The method of Claim 8, said organic gas comprising vinylic hydrocarbons.
10. (original) The method of Claim 8, said organic gas comprising fluorocarbons.
11. (original) The method of Claim 1, said vapor deposition comprising:
 - providing an organic gas;
 - heating said organic gas to generate reactive intermediaries of said organic gas;
 - and
 - depositing said reactive intermediaries on said micromechanical devices.
12. (original) The method of Claim 11, said organic gas comprising a p-xylylene polymer.

13. (original) The method of Claim 11, said organic gas comprising a fluorocarbon polymer.
14. (original) The method of Claim 11, said organic gas comprising hexafluoropropylene oxide.
15. (original) The method of Claim 1, said vapor deposition comprising:
 - providing an organic gas;
 - exposing said organic gas to a heated filament to generate reactive intermediaries of said organic gas; and
 - depositing said reactive intermediaries on said micromechanical devices.
16. (original) The method of Claim 15, said organic gas comprising a p-xylylene polymer.
17. (original) The method of Claim 15, said organic gas comprising a fluorocarbon polymer.
18. (original) The method of Claim 15, said organic gas comprising hexafluoropropylene oxide.
19. (original) The method of Claim 1, said overcoating comprising conformally overcoating said micromechanical device.
20. (original) The method of Claim 1, said overcoating comprising overcoating a micromirror device.
21. (original) The method of Claim 1, said forming comprising forming at least two micromechanical devices on a common silicon substrate.
22. (original) The method of Claim 1, comprising:
 - cleaning separation debris from said devices prior to said removing said overcoat from said micromechanical devices.
23. (original) The method of Claim 1, comprising:
 - testing said micromechanical devices prior to said overcoating.
24. (original) A method of fabricating a micromechanical device, the method comprising:
 - forming at least two micromechanical devices on a common substrate;
 - providing a plasma of an organic gas;
 - generating reactive intermediaries of said plasma;
 - depositing an overcoat of said reactive intermediaries on said micromechanical devices;

- separating said common substrate to separate said micromechanical devices; and
removing said overcoat from said micromechanical devices.
25. (original) The method of Claim 24, said organic gas comprising vinylic hydrocarbons.
26. (original) The method of Claim 24, said organic gas comprising fluorocarbons.
27. (canceled)
28. (canceled)
29. (canceled)
30. (original) A method of fabricating a micromechanical device, the method comprising:
 forming at least two micromechanical devices on a common substrate;
 providing an organic gas;
 exposing said organic gas to at least one electrical conductor held at a high
 voltage potential to generate reactive intermediaries of said organic gas;
 depositing said reactive intermediaries on said micromechanical devices;
 separating said common substrate to separate said micromechanical devices; and
 removing said overcoat from said micromechanical devices.
31. (original) The method of Claim 30, said organic gas comprising vinylic hydrocarbons.
32. (original) The method of Claim 30, said organic gas comprising fluorocarbons.
33. (original) A method of fabricating a micromechanical device, the method comprising:
 forming at least two micromechanical devices on a common substrate;
 providing an organic gas;
 heating said organic gas to generate reactive intermediaries of said organic gas;
 depositing said reactive intermediaries on said micromechanical devices;
 separating said common substrate to separate said micromechanical devices; and
 removing said overcoat from said micromechanical devices.
34. (original) The method of Claim 33, said organic gas comprising a p-xylylene polymer.
35. (original) The method of Claim 33, said organic gas comprising a fluorocarbon polymer.
36. (original) The method of Claim 33, said organic gas comprising hexafluoropropylene
 oxide.
37. (original) A method of fabricating a micromechanical device, the method comprising:

- forming at least two micromechanical devices on a common substrate;
providing an organic gas;
exposing said organic gas to a heated filament to generate reactive
intermediaries of said organic gas;
depositing said reactive intermediaries on said micromechanical devices;
separating said common substrate to separate said micromechanical devices; and
removing said overcoat from said micromechanical devices.
- 38. (original) The method of Claim 37, said organic gas comprising a p-xylylene polymer.
 - 39. (original) The method of Claim 37, said organic gas comprising a fluorocarbon polymer.
 - 40. (original) The method of Claim 37, said organic gas comprising hexafluoropropylene oxide.
 - 41. (newly presented) The method of Claim 1, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said overcoating is sufficient to immobilize said moveable element.
 - 42. (newly presented) The method of Claim 24, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said depositing is sufficient to immobilize said moveable element.
 - 43. (newly presented) The method of Claim 27, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said depositing is sufficient to immobilize said moveable element.
 - 44. (newly presented) The method of Claim 30, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said depositing is sufficient to immobilize said moveable element.
 - 45. (newly presented) The method of Claim 33, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said depositing is sufficient to immobilize said moveable element.
 - 46. (newly presented) The method of Claim 37, said forming comprising forming at least two micromechanical devices having at least one moveable element, wherein said depositing is sufficient to immobilize said moveable element.